

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01286	100.0	0.26839
			Subtotal	0.01286	100	0.26839
Die	Doped silicon	Silicon (Si)	7440-21-3	0.11979	100.0	2.5
			Subtotal	0.11979	100	2.5
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.0105	10.0	0.21909
	Silver alloy	Silver (Ag)	7440-22-4	0.0021	2.0	0.04382
	Lead alloy	Lead (Pb)	7439-92-1	0.09238	88.0	1.92798
			Subtotal	0.10498	100	2.19089
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.05144	100.0	1.07354
			Subtotal	0.05144	100	1.07354
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00704	0.03	0.14694
	Pure metal layer	Zinc (Zn)	7440-66-6	0.00469	0.02	0.09796
	Pure metal layer	Tin (Sn)	7440-31-5	0.00704	0.03	0.14694
	Pure metal layer	Iron (Fe)	7439-89-6	0.02582	0.11	0.53877
	Pure metal layer	Copper (Cu)	7440-50-8	23.42414	99.81	488.8594
			Subtotal	23.46873	100	489.79001
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.24758	100.0	5.167
			Subtotal	0.24758	100	5.167
Mould Compound	Polymer	Tetrabromobisphenol A/Epichlorohydrin polymer	40039-93-8	2.27984	3.0	47.58
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	4.55968	6.0	95.16
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	7.59946	10.0	158.6
	Carbon Black	Carbon black	1333-86-4	0.37997	0.5	7.93
	Filler	Misc. Silica compounds (generic)	14808-60-7	59.2758	78.0	1237.08
	Flame retardant	Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	1.89987	2.5	39.65
			Subtotal	75.99462	100	1586
			Total	100	100	2086.98983

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.